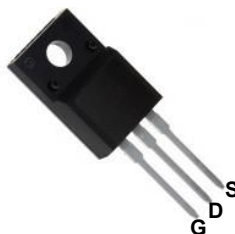
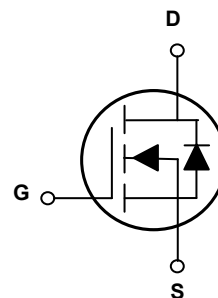


Main Product Characteristics

| | |
|---------------|-------------|
| $V_{(BR)DSS}$ | 650V |
| $R_{DS(ON)}$ | 2.3Ω (Typ.) |
| I_D | 4A |



TO-220F



Schematic Diagram

Features and Benefits

- Advanced MOSFET process technology
- Low on-resistance
- Fast switching and reverse body recovery



Description

The GSFU6504 utilizes the latest techniques to achieve high cell density and low on-resistance. These features make this device extremely efficient and reliable for use in high efficiency switch mode power supplies and a wide variety of other applications.

Absolute Maximum Ratings ($T_C=25^{\circ}C$ unless otherwise specified)

| Parameter | Symbol | Max. | Unit |
|---|-----------------|--------------------|------|
| Drain-Source Voltage | V_{DSS} | 650 | V |
| Gate-Source Voltage | V_{GSS} | ±30 | V |
| Continuous Drain Current | I_D | $T_C=25^{\circ}C$ | 4 |
| | | $T_C=100^{\circ}C$ | 2.5 |
| Pulsed Drain Current ¹ | I_{DM} | 16 | A |
| Single Pulsed Avalanche Energy ² | E_{AS} | 215 | mJ |
| Power Dissipation | P_D | 77 | W |
| Thermal Resistance, Junction to Case | $R_{\theta JC}$ | 1.62 | °C/W |
| Thermal Resistance, Junction to Ambient | $R_{\theta JA}$ | 110 | °C/W |
| Operating and Storage Temperature Range | T_J, T_{STG} | -55 to +150 | °C |

Electrical Characteristics ($T_C=25^\circ\text{C}$ unless otherwise specified)

| Parameter | Symbol | Test Condition | Min. | Typ. | Max. | Unit |
|---|---------------|---|------|------|-----------|----------|
| Off Characteristic | | | | | | |
| Drain-Source Breakdown Voltage | $V_{(BR)DSS}$ | $V_{GS}=0V, I_D=250\mu A$ | 650 | - | - | V |
| Zero Gate Voltage Drain Current | I_{DSS} | $V_{DS}=650V, V_{GS}=0V, T_J=25^\circ\text{C}$ | - | - | 1 | μA |
| Gate to Body Leakage Current | I_{GSS} | $V_{GS}=\pm 30V$ | - | - | ± 100 | nA |
| On Characteristics | | | | | | |
| Gate Threshold Voltage | $V_{GS(th)}$ | $V_{DS}=V_{GS}, I_D=250\mu A$ | 2 | - | 4 | V |
| Static Drain-Source On-Resistance ³ | $R_{DS(on)}$ | $V_{GS}=10V, I_D=2A$ | - | 2.3 | 2.7 | Ω |
| Dynamic Characteristics | | | | | | |
| Input Capacitance | C_{iss} | $V_{DS}=25V, V_{GS}=0V, f=1.0\text{MHz}$ | - | 430 | - | pF |
| Output Capacitance | C_{oss} | | - | 55 | - | pF |
| Reverse Transfer Capacitance | C_{rss} | | - | 4.1 | - | pF |
| Total Gate Charge | Q_g | $V_{DD}=520V, I_D=4A, V_{GS}=10V$ | - | 12.5 | - | nC |
| Gate-Source Charge | Q_{gs} | | - | 2.74 | - | nC |
| Gate-Drain("Miller") Charge | Q_{gd} | | - | 6.31 | - | nC |
| Switching Characteristics | | | | | | |
| Turn-On Delay Time | $t_{d(on)}$ | $V_{DD}=325V, I_D=4A, R_G=25\Omega, V_{GS}=10V$ | - | 9.93 | - | nS |
| Turn-On Rise Time | t_r | | - | 25.6 | - | nS |
| Turn-Off Delay Time | $t_{d(off)}$ | | - | 27.6 | - | nS |
| Turn-Off Fall Time | t_f | | - | 25.6 | - | nS |
| Drain-Source Diode Characteristics and Maximum Ratings | | | | | | |
| Maximum Continuous Drain to Source Diode Forward Current | I_S | - | - | - | 4 | A |
| Maximum Pulsed Drain to Source Diode Forward Current | I_{SM} | | - | - | 16 | A |
| Drain to Source Diode Forward Voltage | V_{SD} | $V_{GS}=0V, I_{SD}=4A, T_J=25^\circ\text{C}$ | - | - | 1.4 | V |
| Reverse Recovery Time | t_{rr} | $V_{GS}=0V, I_S=4A, di/dt=100A/\mu S$ | - | 450 | - | nS |
| Reverse Recovery Charge | Q_{rr} | | - | 1.87 | - | μC |

- Notes: 1. Repetitive Rating: Pulse width limited by maximum junction temperature
2. $I_{AS} = 3.6A, L=30\text{mH}, V_{DD} = 100V, R_G = 25\Omega, \text{starting } T_J = 25^\circ\text{C}.$
3. Pulse Test: pulse width $\leq 300\mu S$, duty Cycle $\leq 1\%$

Typical Electrical and Thermal Characteristic Curves

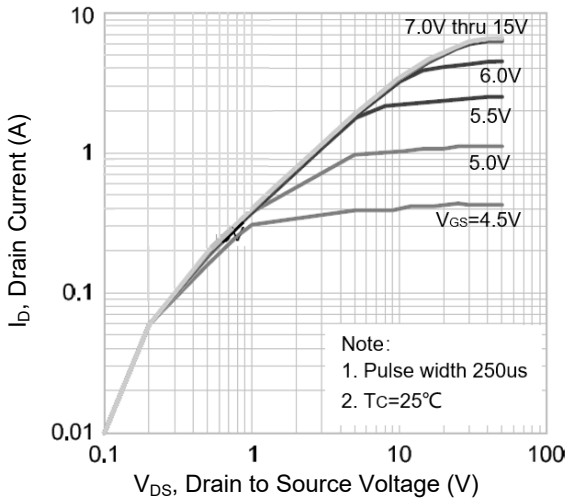


Figure 1. Output Characteristics

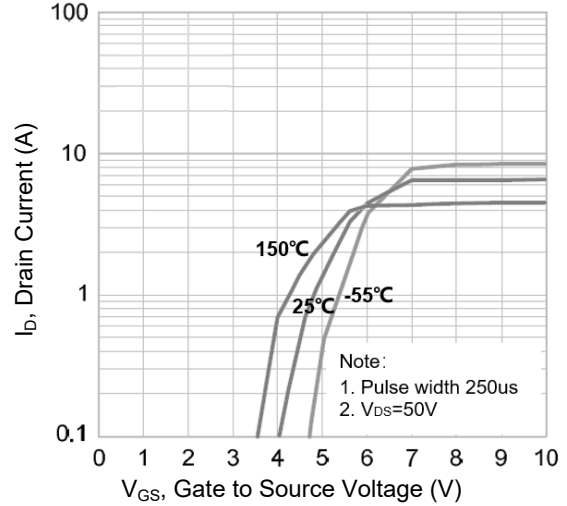


Figure 2. Transfer Characteristics

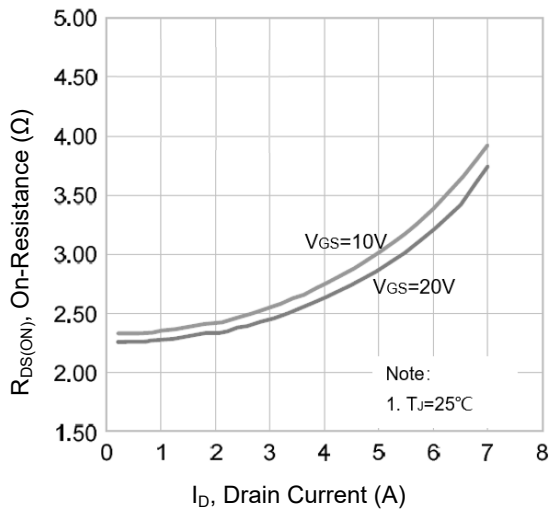


Figure 3. $R_{DS(ON)}$ vs. Drain Current

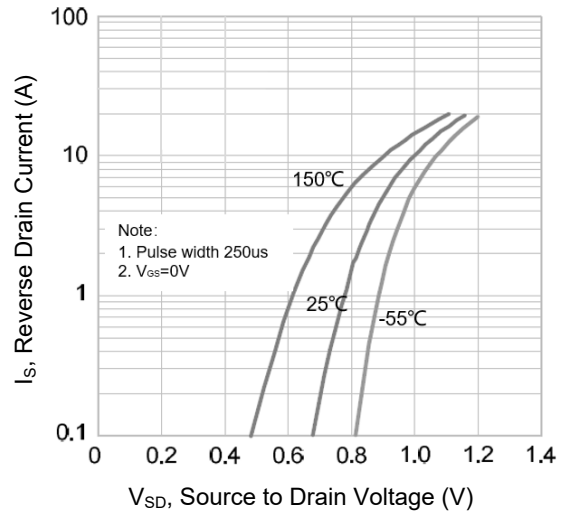


Figure 4. Body Diode Characteristics

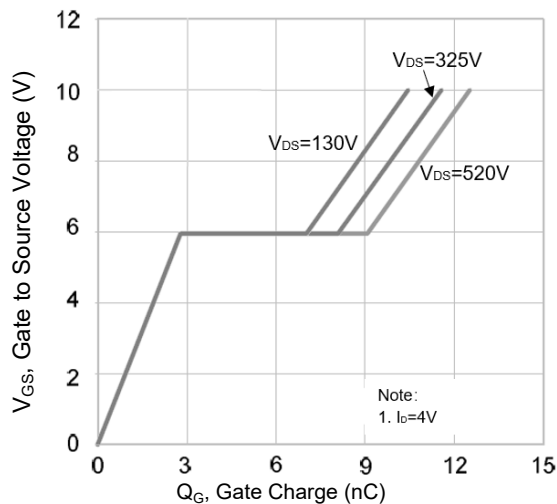


Figure 5. Gate Charge

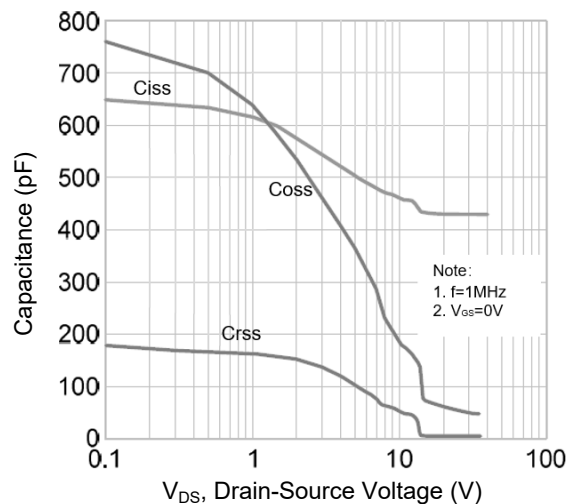


Figure 6. Capacitance Characteristics

Typical Electrical and Thermal Characteristic Curves

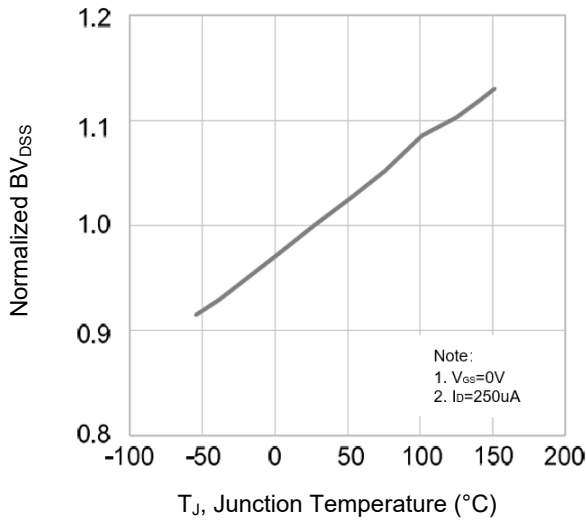


Figure 7. Normalized BV_{DSS} vs. Junction Temperature

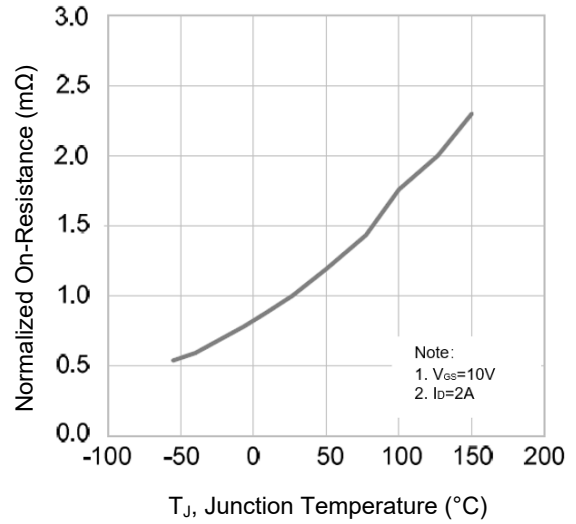


Figure 8. Normalized $R_{DS(ON)}$ vs. Junction Temperature

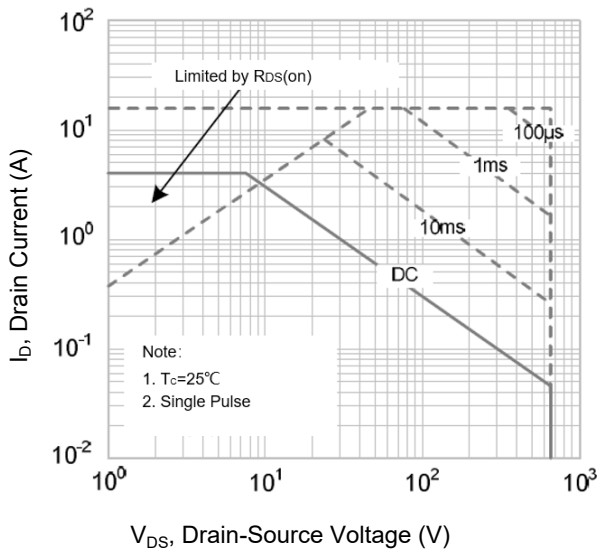


Figure 9. Safe Operation Area

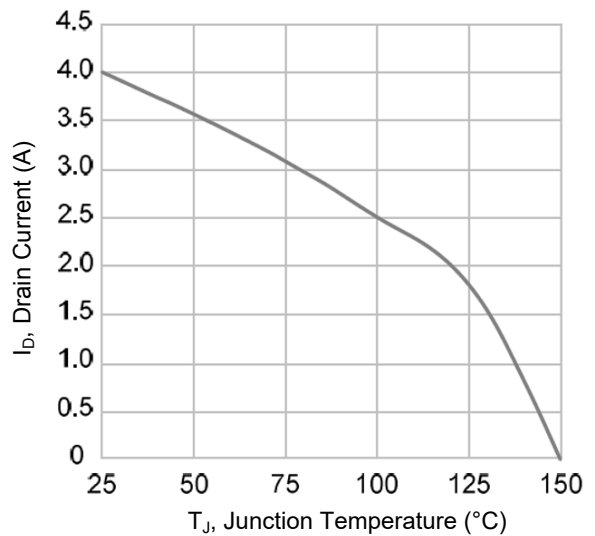
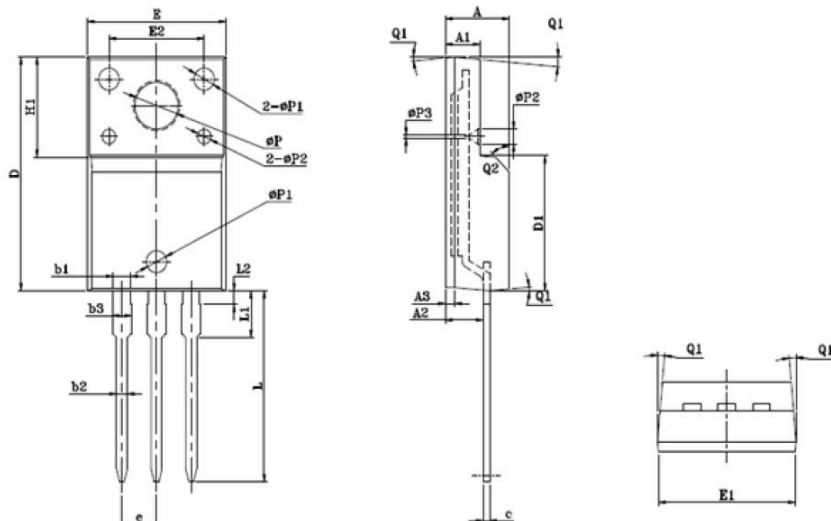


Figure 10. Current De-rating

Package Outline Dimensions (TO-220F)



| Symbol | Dimensions in Millimeters | | Dimensions in Inches | |
|--------|---------------------------|--------|----------------------|-------|
| | Min | Max | Min | Max |
| E | 9.960 | 10.360 | 0.392 | 0.408 |
| E1 | 9.840 | 10.240 | 0.387 | 0.403 |
| E2 | 6.800 | 7.200 | 0.268 | 0.283 |
| A | 4.600 | 4.800 | 0.181 | 0.189 |
| A1 | 2.440 | 2.640 | 0.096 | 0.104 |
| A2 | 2.660 | 2.860 | 0.105 | 0.113 |
| A3 | 0.600 | 0.800 | 0.024 | 0.031 |
| c | 0.500 TYP | | 0.020 TYP | |
| D | 15.780 | 15.980 | 0.621 | 0.629 |
| D1 | 8.970 | 9.370 | 0.353 | 0.369 |
| H1 | 6.500 | 6.800 | 0.256 | 0.268 |
| e | 2.540 BSC | | 0.100 BSC | |
| ØP | 3.080 | 3.280 | 0.121 | 0.129 |
| ØP1 | 1.400 | 1.600 | 0.055 | 0.063 |
| ØP2 | 0.900 | 1.100 | 0.035 | 0.043 |
| ØP3 | 0.100 | 0.300 | 0.004 | 0.012 |
| L | 12.780 | 13.180 | 0.503 | 0.519 |
| L1 | 2.970 | 3.370 | 0.117 | 0.133 |
| L2 | 0.830 | 1.030 | 0.033 | 0.041 |
| Q1 | 3° | 7° | 3° | 7° |
| Q2 | 43° | 47° | 43° | 47° |
| b1 | 1.180 | 1.380 | 0.046 | 0.054 |
| b2 | 0.760 | 0.840 | 0.030 | 0.033 |
| b3 | - | 1.420 | - | 0.056 |